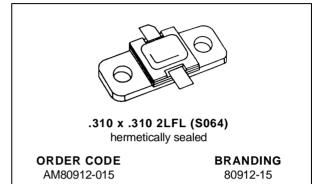
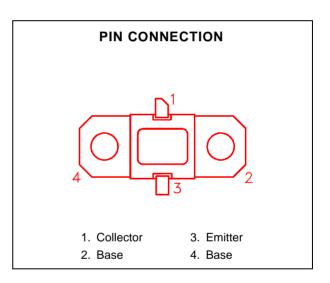


# AM80912-015

# RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- REFRACTORY/GOLD METALLIZATION
- EMITTER SITE BALLASTED
- ∞:1 VSWR CAPABILITY
- LOW THERMAL RESISTANCE
- INPUT MATCHING
- METAL/CERAMIC HERMETIC PACKAGE
- P<sub>OUT</sub> = 15 W MIN. WITH 8.1 dB GAIN
- BANDWIDTH 255 MHz





### DESCRIPTION

The AM80912-015 is designed for specialized avionics applications, including JTIDS, where power is provided under pulse formats utilizing short pulse widths and high burst or overall duty cycles.

The AM80912-015 is housed in the unique IMPAC<sup>TM</sup> Hermetic Metal/Ceramic package with

Symbol	Parameter	Value	Unit	
P <sub>DISS</sub>	Power Dissipation*( $T_C \le 100^{\circ}C$ )	50	W	
Ι <sub>C</sub>	Device Current*	1.8	А	
Vcc	Collector-Supply Voltage*	32	V	
TJ	Junction Temperature (Pulsed RF Operation)	250	°C	
T <sub>STG</sub>	Storage Temperature	- 65 to +200	°C	

# **ABSOLUTE MAXIMUM RATINGS** $(T_{case} = 25^{\circ}C)$

#### THERMAL DATA

R <sub>TH(j-c)</sub> Junction-Case Thermal Resistance*	3.0	°C/W
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\*Applies only to rated RF amplifier operation

# **ELECTRICAL SPECIFICATIONS** ( $T_{case} = 25^{\circ}C$ )

# STATIC

			Value			
Symbol		Test Conditions	Min.	Тур.	Max.	Unit
ВVсво	$I_C = 10 mA$	$I_E = 0mA$	55	—	—	V
BVEBO	$I_E = 1mA$	$I_C = 0 m A$	3.5		—	V
BVCER	IC = 10mA	$R_{BE} = 10\Omega$	55		—	V
ICES	$V_{BE} = 0V$	$V_{CE} = 28V$			2.0	mA
h <sub>FE</sub>	$V_{CE} = 5V$	$I_{C} = 500 \text{mA}$	15		150	_

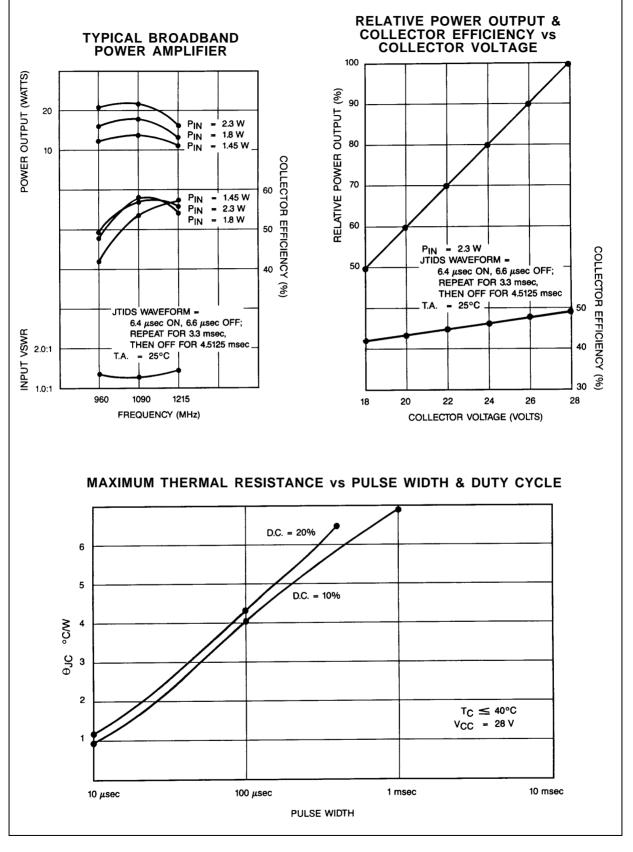
# DYNAMIC

				Value			
Symbol	1	Test Conditions		Min.	Тур.	Max.	Unit
Pout	f = 960 — 1215MHz	$P_{IN}=2.3W$	$V_{CC} = 28V$	15	17		W
ηc	f = 960 — 1215MHz	$P_{IN}=2.3W$	$V_{CC} = 28V$	45	49	_	%
GP	f = 960 — 1215MHz	$P_{IN}=2.3W$	$V_{CC} = 28V$	8.1	8.9		dB

Note: Pulse format: 6.4  $\mu S$  on 6.6  $\mu S$  off, repeat for 3.3 ms, then off for 4.5125 ms. Duty Cycle: Burst 49.2%, overall 20.8%

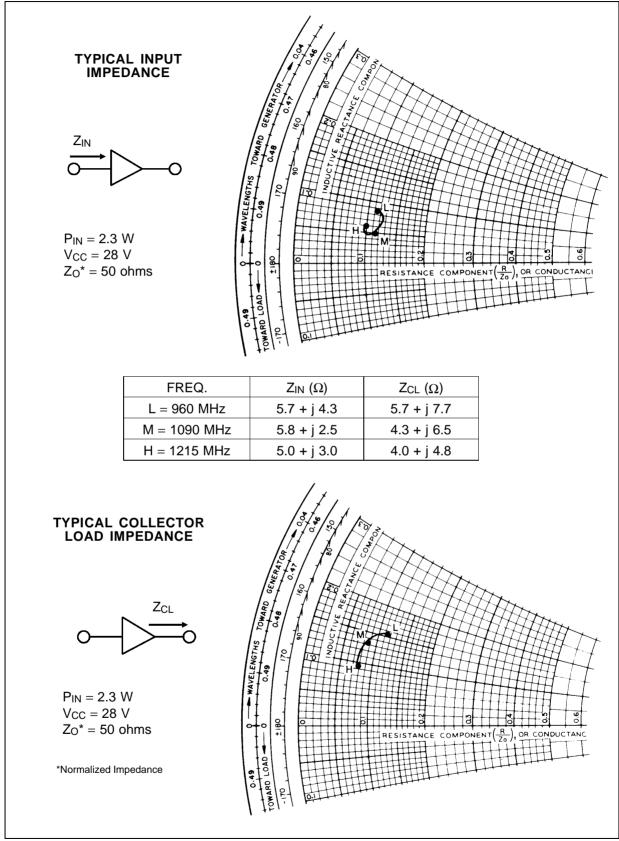


#### **TYPICAL PERFORMANCE**

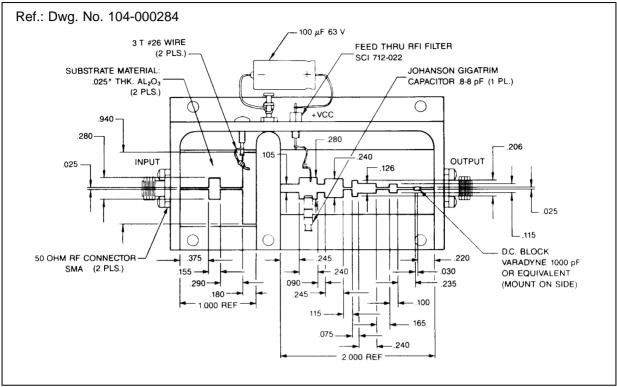




### **IMPEDANCE DATA**

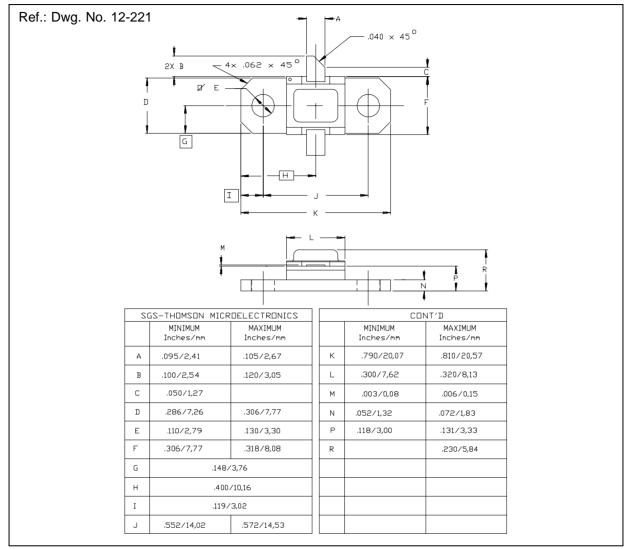


# **TEST CIRCUIT**





#### PACKAGE MECHANICAL DATA



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